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PATENT

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In re application of:
Hunt et al.

Serial No.: 09/283,100

Filed: March 31, 1999

For: FORMATION OF THIN FILM CAPACITORS

: Group Art Unit: 2831

: Examiner: E. Thomas

AMENDMENT, After final

Assistant Commissioner of Patent and Trademarks
US Patent and Trademark Office
Washington, DC 20231

In response to the Official Action mailed on 1 June 2001, Applicants submit the following amendments and remarks.

In the Claims

Claim 5, line 2, change "metal" (second instance) to -copper--.

Claim 6, line 1, change the dependency from "5" to -35--.

Cancel Claims 8 and 9 and Claims 24-28.

Amend Claim 29 and 35 to read as follows:

29. (Amended) A layered structure for forming a thin layer capacitor comprising a metal foil formed of a metal selected from the group consisting of copper, zinc, nickel, iron, niobium, molybdenum, titanium, nickel/chromium alloy, iron/nickel/chromium alloy and aluminum, and a dielectric material deposited on the foil, wherein the dielectric material is a layer having a thickness of from about 0.03 to about 2 microns, said metal foil having an exposed surface and said dielectric material layer having an exposed surface.

35. (amended) A layered structure for acting as or forming at least one thin layer capacitor comprising in sequence a first metal layer selected from the group consisting of copper,